

# **MPF102**

## **N-Channel RF Amplifier**

- This device is designed for electronic switching applications such as low ON resistance analog switching.
- Sourced from process 50.



### 1. Drain 2. Source 3. Gate

# **Absolute Maximum Ratings \*** T<sub>a</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units
$V_{DG}$	Drain-Gate Voltage	25	V
$V_{GS}$	Gate-Source Voltage	-25	V
I <sub>GF</sub>	Forward Gate Current	10	mA
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	- 55 ~ +155	°C

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired

- These ratings are based on a maximum junction temperature of 150 degrees C.
  These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations

# **Electrical Characteristics** T<sub>a</sub>=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
Off Charact	teristics				•
V <sub>(BR)GSS</sub>	Gate-Source Breakdown Voltage	$I_G = -1.0 \mu A, V_{DS} = 0$	-25		V
I <sub>GSS</sub>	Gate Reverse Current	$V_{GS} = -15V, V_{DS} = 0$		-2.0	nA
V <sub>gs(off)</sub>	Gate-Source Cutoff Voltage	$V_{DS} = 15V, I_{D} = 2nA$		-8.0	V
V <sub>gs</sub>	Gate-Source Voltage	$V_{DS} = 15V, I_D = 200\mu A$	-0.5	-7.5	V
On Charact	eristics *				
I <sub>DSS</sub>	Zero-Gate Voltage Drain Current	$V_{DS} = 15V, V_{GS} = 0$	2.0	20	mA
9 <sub>fs</sub>	Forward Transconductance	$V_{GS} = 0V, V_{DS} = 15V, f = 1kHz$	2000	7500	μS
Small Signa	al Characteristics				
C <sub>iss</sub>	Common-Source Input Capacitance	$V_{GS} = 0$ , $V_{DS} = 15V$ , $f = 1MHz$		7.0	pF
C <sub>rss</sub>	Common-Source Reverse Transfer Capacitance	$V_{GS} = 0$ , $V_{DS} = 15V$ , $f = 1MHz$		3.0	pF

# Thermal Characteristics T<sub>a</sub>=25°C unless otherwise noted

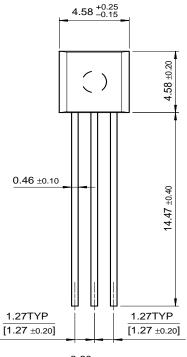
Symbol	Parameter	Max.	Units
P <sub>D</sub>	Total Device Dissipation	350	mW
	Derate above 25°C	2.8	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W

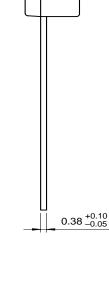
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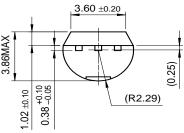


# **Package Dimensions**









Dimensions in Millimeters

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EnSigna™	i-Lo™	OCX™	RapidConfigure™	TruTranslation™
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FACT Quiet Series™		OPTOLOGIC <sup>®</sup>	μSerDes™	UltraFET <sup>®</sup>
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